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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Jason J. Payne et al.  
Serial No.: 10/603,048  
Confirmation No.: 1882  
Filed: June 24, 2003  
For: PRINTED CIRCUIT BOARD FOR HIGH SPEED, HIGH DENSITY ELECTRICAL CONNECTOR WITH IMPROVED CROSS-TALK MINIMIZATION, ATTENUATION AND IMPEDANCE MISMATCH CHARACTERISTICS  
  
Examiner: Nguyen, Hoa Cao  
Art Unit: 2841

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CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

The undersigned hereby certifies that this document is being placed in the United States mail with first-class postage attached, addressed to MAIL STOP AMENDMENT, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the 14th day of October, 2005

  
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Signature

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**MAIL STOP AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Sir:

In response to the Office Action mailed July 14, 2005, please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this amendment.

**Amendments to the Drawings** begin on page 3 of this amendment.

**Amendments to the Claims** are reflected in the listing of claims that begins on page 4 of this amendment.

**Remarks** begin on page 9 of this amendment.